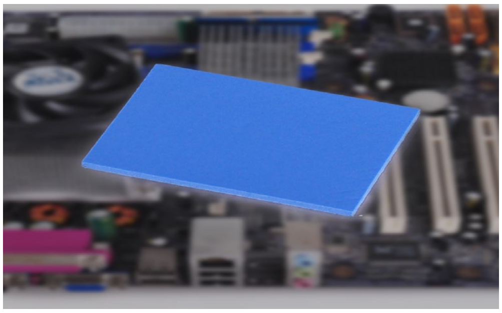
TP300-H50-SF

AOK-TDS-47 Ver:A0

Silicone-free Thermally Conductive Gap Filler Pad

TP300-H50-SF is a silicone-free thermally conductive gap filler pad for high electrical insulation ,excellent thermal conductivity and electrical insulation. It can work stably at -40°C~125°C and meet UL94 V-0 flame retardant grade.



Features

- 3.0 W/(m·K) thermal conductivity
- Silicone-free
- High compression
- Naturally adhesive on both side
- High electrical insulation
- Easy to assemble and reusable

Typical Applications

- Fiber Optic Modules
- Medical Equipment
- Optical precision equipment
- Silicone sensitive components
- Control Modules

Typical Properties

Properties	Attribute	Test Method
Color	Blue	Visual
Thickness(mm)	0.75 to 4.0	ASTM D374
Density(g/cc)	3.0	ASTM D792
Hardness(Shore 00)	50	ASTM D2240
Weight Damnify(%)	⩽1.0	Filter paper adsorption @25% compression,125°C,48h
Usage Temperature(°C)	- 40 to 125	/
Flammability	V-0	UL 94
Shelf Life(month)	12	Temperature <40°C avoid extrusion and exposure to the sun
Electrical		
Breakdown Voltage(kV/mm)	⩾6.0	ASTM D149
Volume Resistivity(Ω·cm)	5×10^{11}	ASTM D257
Dielectric Constant	10.14	ASTM D150
Thermal		
Thermal conductivity(W/(m·K))	3.0	ASTM D5470

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